

1/4-Inch 1.3-Megapixel SOC CMOS Digital Image Sensor

MT9M112 For the latest data sheet, please visit www.sunnywale.com

Features

- Micron[®] DigitalClarity[™] CMOS imaging technology
- System-On-a-Chip (SOC)—Completely integrated camera system
- Ultra-low power, low cost, progressive scan CMOS image sensor
- On-die phase lock loop (PLL)
- Superior low-light performance
- On-die image flow processor (IFP) performs sophisticated processing: Color recovery and correction, sharpening, gamma correction, lens shading correction, and on-the-fly defect correction
- Programmable I/O slew rate
- 2 x 2 pixel binning
- Mechanical shutter support
- Filtered image downscaling to arbitrary size with smooth, continuous zoom and pan
- Fully automatic Xenon- and LED-type flash support
- Automatic Features: Auto exposure, auto white balance (AWB), auto black reference (ABR), auto flicker avoidance, auto color saturation, and auto defect identification and correction
- Multiple parameter contexts, easy/fast mode switching
- Camera control sequencer automates snapshots, snapshots with flash, and video clips
- Simple two-wire serial programming interface
- ITU-R BT.656 (YCbCr), 565RGB, 555RGB, or 444RGB formats (progressive scan)
- Raw and processed Bayer formats
- VDD power disable switch for reduced standby current
- Four general purpose input bond pads

Applications

- Cellular phones
- PDAs
- Toys
- Other battery-powered products

Table 1: Key Performance Parameters

Ordering Information

Table 2: Available Part Numbers

‡Products and specifications discussed herein are for evaluation and reference purposes only and are subject to change by Micron without notice. Products are only warranted by Micron to meet Micron's production data sheet specifications.

^{.99005}aef81e5840a/09005aef81e57f44/9005aef81e57f44/9005aef81e57f44/9005aef81e57f44/90005aef81e57f44/9005aef81e
MT9M112_DS_features1.fm - Rev. B 12/05 EN without notice. هو المستخدم المستخدم المستخدم المستخدم المستخدم المس

 $Preliminary[‡]$

Table of Contents

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Table of Contents

List of Tables

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor List of Figures

List of Figures

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor General Description

General Description

The Micron® Imaging MT9M112 is an SXGA-format, single-chip camera CMOS activepixel digital image sensor. This device combines the 2.8µm image sensor core with fourth-generation digital image flow processor technology from Micron Imaging. It captures high-quality color images at SXGA resolution.

The SXGA CMOS image sensor features DigitalClarity—Micron's breakthrough low-noise CMOS imaging technology that achieves CCD image quality (based on signalto-noise ratio and low-light sensitivity), while maintaining the inherent size, cost, and integration advantages of CMOS.

The sensor is a complete solution designed specifically to meet the low-power, low-cost demands of battery-powered products such as cellular phones, PDAs, and toys. It incorporates sophisticated camera functions on-chip and is programmable through a simple two-wire serial interface.

The MT9M112 performs sophisticated processing functions including color recovery, color correction, sharpening, programmable gamma correction, auto black reference clamping, auto exposure, automatic 50Hz/60Hz flicker avoidance, lens shading correction, auto white balance (AWB), and on-the-fly defect identification and correction. Additional features include day/night mode configurations, special camera effects such as sepia tone and solarization, and interpolation to arbitrary image size with continuous filtered zoom and pan. The device supports both Xenon and LED-type flash light sources in several snapshot modes. The device also has an on-board PLL, and supports pixel binning as an enhanced form of image size reduction.

The MT9M112 can be programmed to output progressive-scan images up to 30 fps. The image data can be output in any one of six 8-bit formats:

- ITU-R BT.656 (formerly CCIR656, progressive scan only) YCbCr
- 565RGB
- 555RGB
- 444RGB
- Raw Bayer
- Processed Bayer

The FRAME_VALID and LINE_VALID signals are output on dedicated signals, along with a pixel clock that is synchronous with valid data.

Functional Overview

The MT9M112 is a fully-automatic, single-chip camera that requires only a power supply, lens, and clock source for basic operation. Output video is streamed through a parallel 8-bit DOUT port as shown in [Figure 1 on page 9.](#page-8-0) The output pixel clock is used to latch data, while FRAME_VALID and LINE_VALID signals indicate the active video. The MT9M112 internal registers are configured using a two-wire serial interface.

The device can be put in a low-power sleep mode by asserting STANDBY and shutting down the clock. Output signals can be tri-stated. Both tri-stating output signals and entry in standby mode also can be achieved through the two-wire serial interface register writes.

The MT9M112 accepts input clocks up to 54 MHz, delivering up to 30 fps for VGA resolution images.

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Functional Overview

Internal Architecture

Internally, the MT9M112 consists of a sensor core and an image flow processor (IFP). The IFP is divided in two sections: the colorpipe (CP) and the camera controller (CC). The sensor core captures raw Bayer-encoded images that are then input in the IFP. The CP section of the IFP processes the incoming stream to create interpolated, color-corrected output, and the CC section controls the sensor core to maintain the desired exposure and color balance and to support snapshot modes. The sensor core, CP, and CC registers are grouped in three separate address spaces as shown in [Figure 2 on page 9](#page-8-1).

When accessing internal registers through the two-wire serial interface, select the desired address space by programming the R0xF0 (R240) register.

The MT9M112 accelerates mode-switching with hardware-assisted context switching and supports taking snapshots, flash snapshots, and video clips using a configurable sequencer.

The MT9M112 supports a range of color formats derived from four primary color representations: YCbCr, RGB, raw Bayer (unprocessed, directly from the sensor), and processed Bayer (Bayer format data regenerated from processed RGB). The device also supports a variety of output signaling/timing options:

- Standard FRAME_VALID/LINE_VALID video interface with gated pixel clocks
- ITU-R BT.656 marker-embedded video interface with either gated or uniform pixel clocks

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Functional Overview

Register Notation

The following register address notations are used in this document:

- R<decimal address>:<address page> Example: R9:0—Shutter width register (register 9) in the sensor page (page 0). Used to uniquely specify a register.
- R0x<3 digit hex address> Example: 0x106 —Mode control in Page 1 register 0x6; leading digit signifies page number.
- Data Format (Binary) Column Key in the Register Summary tables. The following key is used to indicate data format:
	- ? = Read Only
	- $d = Read/Write$
	- 0 = Reserved; read 0; must write 0
	- $1 =$ Reserved; read 1; must write 1
	- r = Reserved; must write back value read
- The following key is used to indicate default value
	- X = Indeterminate Register Default Values

Register Definition Table

The register definition tables contain the power-on default values for the bit fields and registers of the MT9M112. Modifying these values may [affect or degrade] the performance of the MT9M112. See the individual register descriptions for more detail.

Reserved Registers

Do not alter the reserved registers. If some bits or bit patterns (that is, bit field values) in a register are reserved, they cannot be used. Do not set bit fields to reserved or undefined bit patterns as Micron will not guarantee operation.

The sensor registers are summarized in [Table 12 on page 22.](#page-21-2) The colorpipe registers are summarized in [Table 13 on page 26.](#page-25-2) The camera control registers are summarized in [Table 14 on page 29](#page-28-1).

Detailed register descriptions are given in [Table 15 on page 33](#page-32-2), [Table 16 on page 48](#page-47-2), and [Table 17 on page 64](#page-63-2).

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Functional Overview

Figure 1: Functional Block Diagram

Note: Each of the general purpose input only signals (GPI0–GPI3) must be connected to either DGND or VDDQ for low-power consumption and reliable operation

Figure 2: Internal Registers Grouping

Note: Internal registers are grouped in three address spaces. Register R0xF0 (R240) in each page selects the desired address space.

Typical Connections

[Figure 3](#page-9-1) shows typical MT9M112 device connections. For low-noise operation, the MT9M112 requires separate power supplies for analog and digital. Incoming digital and analog ground conductors can be tied together next to the die. Both power supply rails must be decoupled to ground using capacitors as close as possible to the die. The use of inductance filters is not recommended on the power supplies or output signals.

The MT9M112 also supports different digital core (VDD/DGND) and I/O power (VDDQ/ DGND) power domains that can be at different voltages. PLL requires a clean power source (VDDPLL).

Figure 3: Typical Configuration (Connection)

- however, greater values may be used for slower transmission speeds.
	- 2. MT9M112 STANDBY can be connected to the customer's ASIC controller directly, or to digital GND, depending on the capability of the controller.
	- 3. The PLL bypass capacitor should be connected to VDDPLL and DGND.

 MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Signal Descriptions: Inputs, Outputs and Supply

Signal Descriptions: Inputs, Outputs and Supply

Table 3: Signal Description

All inputs and outputs are implemented with bidirectional buffers. Care must be taken that all inputs are driven to avoid floating nodes.

Refer to the MT9M112 die data sheet (1/4-inch 1.3-Megapixel SOC Digital Image Sensor Die Features) document for pad number information.

General Purpose Inputs

Logic levels of four general purpose inputs GPI0-GPI3 may be read through the two-wire serial interface facilitating packaging identification. These signals must be terminated to either VDDQ or DGND to ensure that they are not floating.

Architecture Overview

The MT9M112 IFP consists of a color processing pipeline and a measurement and control logic block (the camera controller). The stream of raw data from the sensor enters the pipeline and undergoes several transformations. Image stream processing starts with conditioning the black level and applying a digital gain. The lens shading block compensates for signal loss caused by the lens. Next, the data is interpolated to recover missing color components for each pixel. The resulting interpolated RGB data passes through the current color correction matrix (CCM), saturation, and gamma corrections and is formatted for final output.

The measurement and control logic continuously accumulate image brightness and color statistics. Based on these measurements, the IFP calculates updated values for exposure time and sensor analog gains that are sent to the sensor core through the control ring bus. The camera control unit also automates taking snapshots, flash snapshots, and video clips using a hardware sequencer.

Black Level Conditioning

The sensor core black clamp control works to maintain black pixel values at a constant level, independent of analog gain, reference current, voltage settings, and temperature conditions. If this black level is above zero, it must be reduced before color processing can begin. The black level subtraction block remaps the black level, or pedestal, of the sensor to zero prior to lens shading correction. Following lens shading correction, the black level addition block provides capability for another black level adjustment. However, for good contrast, this level should be set to zero.

Digital Gain and Test Pattern

Controlled by auto exposure logic, the input digital gain stage amplifies the raw image in low-light conditions. A built-in test pattern generator produces a test image stream that can be multiplexed at the output of the gain stage.

Figure 4: IFP Block Diagram

Lens Shading Correction

Inexpensive lenses tend to attenuate image intensity near the edges of pixel arrays. Other factors also cause signal and coloration differences across the image. The net result of all these factors is known as lens shading. Lens shading correction (LC) compensates for these differences.

Typically, the profile of lens shading induced anomalies across the frame is different for each color component. Lens shading correction is independently calibrated for each of the RGB color channels.

The lens shading correction module incorporates a first exposure controlled digital gain, a second auto exposure controlled digital gain, and black level adjustments.

Interpolation, Filtered Resize, and Aperture Correction

A demosaic engine converts the single color per pixel Bayer data from the sensor into 30-bit RGB pixels. The demosaic algorithm analyzes neighboring pixels to generate a best guess for the missing color components. Edge sharpness is preserved as much as possible. Green balance compensation is added to mask the symptoms of green imbalance.

A resize engine uses weighted sampling to smoothly reduce the image by any number of pixels or lines. A digital pixel averaging or binning module extends the reduction range to 10x or more without aliasing. Both reduction engines are set up automatically in hardware so the software driver just has to load the desired output image size and zoom window.

Automatic zoom with single bit zoom-in and zoom-out controls emulates zoom lens behavior. The zoom rate is programmable to optimize zoom response for each application.

Reducer and zoom window changes are synchronized so the reducer and zoom programming do not have to be coordinated with video frame timing. Zoom slow steps the zoom window only on every other frame, allowing auto exposure more time to adapt to each zoom window change.

Aperture correction sharpens the image by an adjustable amount. Sharpening can be programmed to phase out as light levels drop to avoid amplifying noise.

Defect Correction

The MT9M112 has 2D defect correction where pixels with values different from their neighbors by a programmable threshold are considered defects and are replaced.

Color Correction

To obtain good color rendition and saturation, it is necessary to compensate for the differences between the spectral characteristics of the imager color filter array and the spectral response of the human eye. This compensation is achieved through linear transformation of the image with a 3 x 3 element color correction matrix. Optimum values for the color correction coefficients depend on the spectrum of the incident illumination and can either be programmed by the user, or automatically selected by the AWB algorithm described in ["Automatic White Balance \(AWB\)" on page 16.](#page-15-2)

3-Channel Gamma Correction

A separate gamma correction function operates on each of the R, G, and B components of the image and enables compensation for nonlinear dependence of the display device output versus driving signal (for example, monitor brightness versus CRT voltage).

In addition, gamma correction provides range compression, converting 10-bit R, G, B input to 8-bit output. Pre-gamma image processing generates 10-bit R, G, B values ranging from 0 to 1024 inclusive. Piecewise linear gamma correction utilized in this imager has eleven intervals, with end points corresponding to the following input values:

 $Xi = 0...11 = \{0,16,32,64,128,256,384,512,640,768,896,1024\}$

For each input value XI, the user can program the corresponding output value YI. YI values which must be non-decreasing. The MT9M112 supports two context-switchable gamma tables.

Figure 5: Gamma Correction Curve

Color Saturation Control

The MT9M112 supports gradual color saturation reduction in the brightest areas of the image, helping eliminate color artifacts related to clipped pixel values. For noise reduction, both color saturation and sharpness enhancement can be set by the user or adjusted automatically by tracking the magnitude of the gains used by the auto exposure algorithm. Color saturation may be scaled by a constant value of either 0 percent (black and white), 25 percent (1/4), 37.5 percent (3/8), 50 percent (1/2), 75 percent (3/4), 100 percent (1/1), 112.5 percent (9/8), 125 percent (5/4), 137.5 percent (11/8), and 150 percent (3/2).

ITU-R BT.656 and RGB Output

The MT9M112 outputs processed video as a standard ITU-R BT.656 stream, an RGB stream, or as processed or unprocessed Bayer data. The ITU-R BT.656 stream contains YCbCr 4:2:2 data with optional embedded synchronization codes. This output is typically suitable for subsequent display by standard video equipment or JPEG/MPEG compression. RGB functionality provides support for LCD devices.

The MT9M112 can be configured to output 16-bit RGB (RGB565), 15-bit RGB (RGB555), and two types of 12-bit RGB (RGB444). The user can configure internal registers to swap odd and even bytes, chrominance channels, and luminance and chrominance components to interface with application processors. Refer to [Table 4 on page 19](#page-18-1) through [Table 11 on page 20](#page-19-3) for more details.

Details of Bayer Output

Unprocessed Bayer data is generated when bypassing the SOC IFP completely. The raw sensor Bayer data stream can be timed using FRAME_VALID, LINE_VALID, and PIXCLK.

In processed Bayer mode, processed RGB is resampled to reduce the data rate by half. Each internal RGB pixel is converted to the 8-bit value of one of the colors: R, G, or B. The pixel pattern is the same as conventional Bayer data, for example GRGR… on one line followed by BGBG… on the next. The receiver interpolates the pixel data to recover the automatically exposed and white balanced image data.

Additional Output Timing Formats

In addition to the color formats detailed above, the MT9M112 supports a number of output timing formats.

Standard: This format includes standard data output, FRAME_VALID, LINE_VALID, and pixel clock signaling. The pixel clock runs continuously, but is gated high for invalid pixel values occurring during an active line. Pixel clock gating occurs when the pixel rate is less than the maximum allowed by the clock—this is typical during preview mode or output image resizing.

ITU-R BT.656: ITU-R BT.656 with synchronization codes. Pixel data is again timed with pixel clock, but FRAME_VALID and LINE_VALID are exchanged for synchronization codes embedded in the pixel stream.

Inactive Pixel Clock: A variant on the standard format, where the pixel clock is gated inactive during both horizontal blanking and vertical blanking.

Automatic White Balance (AWB)

The MT9M112 has a built-in AWB algorithm designed to compensate for the effects of changing scene illumination on the quality of the color rendition. This sophisticated algorithm consists of three major submodules:

- A measurement engine (ME) performing statistical analysis of the image.
- A module selecting the optimal color correction matrix and analog color channel gains in the sensor core.
- A color channel gain control module that fine tunes the color correction matrix and determines the digital gains in the colorpipe.

While the default algorithm settings are adequate in most situations, the user can reprogram base and delta color correction matrices, limit color channel gains, and control the speed of both matrix and gain adjustments. The AWB does not attempt to locate the brightest or grayest elements in the image; it performs in-depth image analysis to differentiate between changes in predominant spectra of illumination and changes in predominant scene colors. Factory defaults are suitable for most applications. However, a wide range of algorithm parameters can be overwritten by the user through the serial interface.

The MT9M112 includes specific, dedicated support for flash photography by means of a flash color correction matrix position. The matrix at the flash matrix position matches the illumination characteristics of the desired LED or Xenon flash. In concert with the auto exposure unit, a decision is made during the sequencing of the flash snapshot as to whether to use the flash matrix (for example, for LEDs, where the flash matrix is only used when it is known if the scene illumination changed significantly).

Auto Exposure

The auto exposure algorithm performs automatic adjustments to image brightness by controlling exposure time and analog gains in the sensor core, as well as digital gain applied to the image. The algorithm relies on the auto exposure measurement engine that tracks speed and amplitude changes in the overall luminance of selected windows in the image. Backlight compensation is achieved by weighting the luminance in the center of the image higher than the luminance on the periphery. Other algorithm features include fast-fluctuating illumination rejection (time averaging), response-speed control, and controlled sensitivity to small changes. While the default settings are adequate in most situations, the user can program target brightness, measurement window, and other parameters, as described above. The auto exposure algorithm enables compensation for a broad range of illumination intensities, with overall range-of-adjustment better than 192,000:1.

The MT9M112 introduces a new auto exposure algorithm that uses a dynamically varying luma target. Alternatively, this algorithm can be turned off and classic auto exposure would take effect.

The MT9M112 also includes fast adaptation modes that are key for LED flash adaptation where convergence within three frames is critical. These modes are used only with classic auto exposure, which is the recommended option when operating flash.

Adaptation mode selection is context-switchable—for example, slower mode for preview video and fast adaptation for flash snapshots. See [Contexts and Context Switching](#page-16-3) below.

Automatic Flicker Detection

Flicker occurs when integration time is not an integer multiple of the period of the light intensity. Automatic flicker detection block does not compensate for the flicker; it reduces flicker occurrence by detecting flicker frequency and adjusting the integration time. For integration times shorter than the light intensity period (10ms for 50Hz environments and 8.33ms for 60Hz environments), flicker is unavoidable.

Flash Light Control

The MT9M112 supports both LED and Xenon-type flash light sources using a dedicated output signal. For Xenon devices, the signal generates a SHUTTER signal to fire when the imager shutter is fully open. For LED, the signal can be asserted or deasserted asynchronously. Flash modes can be configured and engaged over the two-wire serial interface. The flash can be fired either under user control through the two-wire serial interface or by the camera control sequencer. Up to 256 snapshot frames can be captured after the flash is triggered.

Contexts and Context Switching

For a number of parameters in the MT9M112, registers for the storage of two contexts are provided—context A and context B. This enables the user to set up the camera for a number of different modes and then switch between them with a single register write to one of two context control registers (CCRs). Each bit in a CCR typically controls the context of one parameter. Examples of context-switchable parameters include zoom and resize settings, auto exposure speed and algorithm selection, gamma correction table, and output format. Arming a Xenon flash and turning an LED on or off are also considered contexts.

Camera Control Sequencer

Output Data Ordering

The following tables describe the output data order depending on the mode selected.

Table 4: Data Ordering in YCbCr Mode

Table 5: Output Data Ordering in Processed Bayer Mode

Table 6: Output Data Ordering in RGB Mode

Table 7: Output Data Ordering in (8 + 2) Bypass Mode

Table 8: Bayer Output Order R0x108[1:0] = 00

Table 9: Bayer Output Order R0x108[1:0] = 01

Table 10: Bayer Output Order R0x108[1:0] = 10

Table 11: Bayer Output Order R0x108[1:0] = 11

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor MT9M112 Registers

MT9M112 Registers

Double-Buffered Registers

Some sensor settings cannot be changed during frame readout. For example, changing row width R0x003 part way through frame readout results in inconsistent LINE_VALID behavior. To avoid this, the MT9M112 double-buffers many registers by implementing a pending and a live version. Reads and writes access the pending register; the live register controls the sensor operation.

The value in the pending register is transferred to a live register at a fixed point in the frame timing called frame start. Frame start is defined as the point at which the first dark row is read out. By default, this occurs ten row times before FRAME_VALID goes high. R0x022 enables the dark rows to be shown in the image, but this has no effect on the position of frame start.

To determine which registers or register fields are double-buffered in this way, see the synd'c-to-frame start column in [Table 15 on page 33](#page-32-2).

R0x00D[15] can be used to inhibit transfers from the pending to the live registers. Use this control bit when making many register changes that must take effect simultaneously.

Bad Frames

A bad frame is a frame where all rows do not have the same integration time, or where offsets to the pixel values changed during the frame.

Many changes to the sensor register settings can cause a bad frame. For example, when row width R0x003 is changed, the new register value does not affect sensor behavior until the next frame start. However, the frame that would be read out at that frame start has been integrated using the old row width. Consequently, reading it out using the new row width results in a frame with an incorrect integration time.

By default, most bad frames are masked: LINE_VALID and FRAME_VALID are inhibited for these frames, so that the vertical blanking time between frames is extended by the frame time.

To determine which register or register field changes can produce a bad frame, see [Table 15 on page 33](#page-32-2), the bad frame column, and these notations:

- N—No. Changing the register value does not produce a bad frame.
- Y—Yes. Changing the register value might produce a bad frame.
- YM—Yes; but the bad frame is masked out unless the show bad frames feature (R0x00D[8])is enabled.

Sensor Core Registers – Summary

Register addresses that do not appear in the summary tables are not used by the MT9M112. A summary of the sensor core registers is shown in [Table 12](#page-21-1).

Table 12: Page 0: Sensor Core Register Summary

Table 12: Page 0: Sensor Core Register Summary (continued)

Table 12: Page 0: Sensor Core Register Summary (continued)

Table 12: Page 0: Sensor Core Register Summary (continued)

 MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Image Flow Processing Registers – Summary

Image Flow Processing Registers – Summary

Register addresses that do not appear in the summary tables are not used by the MT9M112. A summary of the Image Flow Processing registers is shown in [Table 13](#page-25-1).

Table 13: Page 1: Image Flow Processing Register Summary

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Image Flow Processing Registers – Summary

Table 13: Page 1: Image Flow Processing Register Summary (continued)

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Image Flow Processing Registers – Summary

Table 13: Page 1: Image Flow Processing Register Summary (continued)

Camera Control Registers – Summary

Register addresses that do not appear in the summary tables are not used by the MT9M112. A summary of the Camera Control Processing registers is shown in [Table 14.](#page-28-0)

Table 14: Page 2: Camera Control Register Summary

Table 14: Page 2: Camera Control Register Summary (continued)

Table 14: Page 2: Camera Control Register Summary (continued)

Table 14: Page 2: Camera Control Register Summary (continued)

Page 0: Sensor Core Register Descriptions

Table 15: Page 0: Sensor Core Register Descriptions

Data format: RO = Read Only; RW = Read/Write (R/W); Hex = Hexadecimal; – = Reserved; X = Indeterminate

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Data format: RO = Read Only; RW = Read/Write (R/W); Hex = Hexadecimal; - = Reserved; X = Indeterminate

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Data format: RO = Read Only; RW = Read/Write (R/W); Hex = Hexadecimal; - = Reserved; X = Indeterminate

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Data format: RO = Read Only; RW = Read/Write (R/W); Hex = Hexadecimal; - = Reserved; X = Indeterminate

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Table 15: Page 0: Sensor Core Register Descriptions (continued)

Data format: RO = Read Only; RW = Read/Write (R/W); Hex = Hexadecimal; - = Reserved; X = Indeterminate

Notes: 1. R0x00B: Unless integration time is less than one frame.

2. R0x0C0[15]: Will cause current frame to stop if triggered during a frame.

Page 1: Image Processing Register Descriptions

Table 16: Page 1: Image Processing Register Descriptions

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Table 16: Page 1: Image Processing Register Descriptions (continued)

Page 2: Camera Control Register Descriptions

Table 17: Page 2: Camera Control Register Descriptions

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

Table 17: Page 2: Camera Control Register Descriptions (continued)

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Reset, Clocks, and Low Power Modes

Reset, Clocks, and Low Power Modes

There are no constraints concerning the order in which the various power supplies are applied; however, the MT9M112 requires reset in order to operate properly at power-up. Refer to the [Figure 6](#page-98-0) for the power-up, reset, and standby sequences.

 $R0x00D[4] = 0$, $R0x00D[6] = 0$

- Notes: 1. All output signals are defined during initial power-up with RESET# = 0 without CLKIN being active. For a proper reset sequence for the rest of the sensor, during initial powerup, assert RESET# = 0 for at least $1 \mu S$ after all power supplies have stabilized and CLKIN is active (being clocked). Driving RESET# $= 0$ does not put the part in a low power state.
	- 2. In Hard standby the output signals are high impedance by default. The output state is controlled by register R0x00D settings.
	- 3. Soft standby is asserted or deasserted by a two-wire serial interface to R0x00D[2]. In this mode, the analog clock and the internal clocks are shut off. The output signals are not high impedance by default. The total leakage currents can be lowered if the two-wire serial interface and the CLKIN are turned OFF after 80 CLKIN cycles after issuing soft standby.
	- 4. Wait for 10 CLKIN rising edges after RESET# is deasserted before using two-wire serial interface.
	- 5. Illustration not drawn to scale (do not count number of clock pulses).

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Reset, Clocks, and Low Power Modes

Note: Illustration not drawn to scale (do not count number of clock pulses).

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Reset, Clocks, and Low Power Modes

VDD Disable Feature

The VDD_DIS signal is used to shut down digital core VDD reducing the power consumption significantly during standby. All register settings are lost. However, the output signal states are maintained as long as VDDQ is maintained. Output signals must be configured appropriately during the standby sequence. Input signal transitions (including RESET#) during VDD_DIS = 1 are ignored.

Proper shutdown and recovery sequences must be followed for minimum power consumption.

Disable and enable the core VDD using the VDD_DIS signal with the following sequences.

To Enter Low Power State

- 1. PLL bypass R0x065[15] = 1
- 2. PLL into standby/power down
- 3. Enter standby mode (hardware or software)
- 4. Assert VDD_DIS
- 5. Stop CLKIN
- 6. Deassert STANDBY if asserted
- 7. The part is now in a core VDD shutdown low power state

To Exit Low Power State

- 1. Assert RESET# (optional)
- 2. Assert STANDBY if the output must be high impedance during start-up
- 3. Deassert VDD_DIS
- 4. Start CLKIN
- 5. Deassert RESET# (if asserted in step 1 above) and start up the sensor

Micron Confidential and Proprietary **Preliminary[‡]** Preliminary[‡]

PLL Operation

The sequence to turn on PLL is:

- 1. After the chip power on reset, PLL is in bypass mode by default.
- 2. Program PLL parameters M, N, and P in R0x066 and R0x067 depending on the external clock frequency and target clock frequency. PLL output clock frequency (f OUT) is calculated with the following equation:

$$
f_{OUT} = f_{CLKIN} \times M \times \left(\frac{1}{2 \times (N+1) \times (P+1)}\right)
$$
 (EQ1)

Where ^fCLKIN is external clock frequency, N is pre-divider and P is post-divider. Both registers have a default value of "1."

- 3. Wake up PLL by programming $R0x065[14] = 0$.
- 4. Wait at least 1ms for PLL to stabilize.
- 5. Program R0x065[15] = 0 to enable PLL output to clock core and release PLL bypass.

Electrical Specifications

DC Electrical Specification

[Table 18](#page-102-0) defines the main power supply voltages and operating conditions of the MT9M112.

Table 18: DC Electrical Characteristics and Operating Conditions

Setup conditions: $T_1 = -30^{\circ}C$ to $+70^{\circ}C$, unless otherwise specified.

Note: 1. Power consumption numbers do not include power from VDDQ.

I/O Parameters

[Table 19](#page-103-0) and [Table 20](#page-103-1) define threshold parameters for voltage and current on input and output signals.

Table 19: I/O Min/Max Parameters (VDDQ = 1.8V)

Setup conditions: VDD = 1.8V, VDDQ = 1.8V, VAA = 2.8V, VAAPIX = 2.8V, VDDPLL = 2.8V, T_1 = -30°C to +70°C, unless otherwise specified.

Table 20: **I/O Min/Max Parameters (VDDQ = 2.8V)**

Setup conditions: $VDD = 2.8V$, $VDDQ = 2.8V$, $VAA = 2.8V$, $VAAPIX = 2.8V$, $VDDPLL = 2.8V$, T_1 = -30°C to +70°C, unless specified otherwise

AC Electrical Specification

[Figure 8](#page-104-0) and [Figure 9](#page-104-1) illustrate clock and I/O timing and show the timing relationships that are defined in [Table 21 on page 106](#page-105-0).

Figure 8: Clock Rise and Fall Timing

Figure 9: I/O Timing Diagram

- Notes: 1. See Figure 8 for Rise and Fall Timing details.
	- 2. PLL disabled for ^tCP. PIXCLK is in phase with CLKIN with propagation delay of ^tCP by default (solid line) and could be inverted (dashed line).

Timing Parameters (1.8V)

[Table 21](#page-105-0) defines timing parameters for the main clocks and the timing relationship between clocks and valid data.

Table 21: I/O Timing Parameters (VDDQ = 1.8V)¹

AC Setup Conditions: ^fCLKIN = 48 MHz, VDD = 1.8V, VDDQ = 1.8V, VAA = 2.8V, VAAPIX = 2.8V, VDDPLL = 2.8V, Output Load = 15pF, T_1 = -30°C to +70°C, unless otherwise specified.

Notes: 1. Output signals DOUT(7:0), LINE_VALID (LV), and FRAME_VALID (FV) are not synchronized with PIXCLK and thus may lag or lead PIXCLK. Therefore, ^tPDV, ^tDVP, ^tPFH, ^tPLH, and ^tPFL may be positive or negative.

- 2. Two PIXCLK cycles are missing prior to falling edge of LV. t PLL for PIXCLK = 48 MHz.
- 3. Slew rates for input clock rising edge $(5R)$ and falling edge $(5R)$ CF) should not differ by more than 10%.

Timing Parameters (2.8V)

Table 22: I/O Timing Parameters (VDDQ = 2.8V)¹

AC Setup Conditions: ^fCLKIN = 48 MHz, VDD = 1.8V, VDDQ = 2.8V, VAA = 2.8V, VAAPIX = 2.8V, VDDPLL = 2.8V, Output Load = 15pF, T_1 = -30°C to +70°C, unless otherwise specified.

Notes: 1. Output signals DOUT(7:0), LINE_VALID (LV), and FRAME_VALID (FV) are not synchronized with PIXCLK and thus may lag or lead PIXCLK. Therefore, ^tPDV, ^tDVP, ^tPFH, ^tPLH, and ^tPFL may be positive or negative.

2. Two PIXCLK cycles are missing prior to falling edge of LV. t PLL for PIXCLK = 48 MHz.

3. Slew rates for input clock rising edge (SRICR) and falling edge (SRICF) should not differ by more than 10%.

Output Signal Slew Rate Control (1.8V)

[Table 23](#page-107-0) and [Table 24](#page-107-1) show the codes for adjusting the slew rate of output signals.

Table 23: Output Signal Slew Rate (1.8V)

Setup conditions: VDDQ = 1.8V, Output Load CLOAD = 15pF, T_J = -30°C to +70°C, unless otherwise specified.

Output Signal Slew Rate Control (2.8V)

Table 24: Output Signal Slew Rate (2.8V)

Setup conditions: VDDQ = 2.8V, Output Load CLOAD = 15pF, T_J = -30°C to +70°C, unless otherwise specified.

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Electrical Specifications

Two-Wire Serial Interface Specification

The following diagrams illustrates the Two-Wire Serial Interface bus timing.

Figure 10: Two-Wire Serial Interface Timing Diagram

Figure 11: Two-Wire Serial Interface Start and Stop Condition Timing

Table 25: Two-Wire Serial Interface Timing

 f SCLK = 400KHz, VDD = 1.8V, VAA = 2.8V, VAAPIX = 2.8V, VDDQ = 2.8V, T_J = -30°C to +70°C, unless otherwise specified.

Absolute Maximum Ratings

Table 26: Absolute Maximum Ratings

Note: Stresses greater than those listed may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may adversely affect reliability.

Spectral Characteristics

Figure 12: Typical Spectral Characteristics

8000 S. Federal Way, P.O. Box 6, Boise, ID 83707-0006, Tel: 208-368-3900 prodmktg@micron.com [www.micron.com Customer Comment Line: 800-932-4992](http://www.micron.com/) Micron, the M logo, and the Micron logo are trademarks of Micron Technology, Inc. All other trademarks are the property of their respective owners. Preliminary: This data sheet contains initial characterization limits that are subject to change upon full characterization of production devices.

MT9M112: 1/4-Inch 1.3-Mp SOC Digital Image Sensor Revision History

Revision History

Sales: Shenzhen Sunnywale Inc, www.sunnywale.com, awin@sunnywale.com, Wechat: 9308762